

INFORMATION

CODE : Q13FC1350000400

MODEL : FC-135 32.768000KHz 12.5PF
 $\pm 20\text{PPM}$

DATE : NOV.20.2012

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INTRODUCTION

1. The contents is subject to change without notice.
Please exchange the specification sheets regarding the product's warranty.
2. This sheet is not intended to guarantee or provide an approval of implementation of industrial patents.
3. We have prepared this sheet as carefully as possible.
If you find it incomplete or unsatisfactory in any respect, We would welcome your comments.

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This product listed here is designed as components or parts for electronics equipment in general consumer use. We do not expect that any of these products would be incorporated or otherwise used as a component or part for the equipment, which requires an extra high reliability, such as satellite, rocket and other space systems, and medical equipment, the functional purpose of which is to keep life.

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[1] Absolute maximum ratings

Item	Symbol	Rating value
Storage temperature	TSTG	-55°C to +125°C
Maximum drive level	DL	1.0 μW

[2] Operating range

Item	Symbol	Value		
		Min.	Typ.	Max.
Operating temperature range	TOPR	-40°C		+85°C
Drive level	DL	0.01 μW	0.1 μW	0.5 μW
Vibration mode		Fundamental		

[3] Static characteristics

Item	Symbol	Value	Note
Frequency	fi	32.768 kHz	
Frequency tolerance	Δ f/f	± 20 × 10 ⁻⁶	CL = 12.5 pF Ta = +25 ± 3°C, Drive level : 0.1 μW Not include aging
Series resistance	R1	70 kΩ Max.	CI meter : Saunders 140B Drive level : 0.5 μW
Motional capacitance	C1	Typ. 3.4 fF	
Shunt capacitance	C0	Typ. 1.2 pF	
Turnover temperature	θT	+25 ± 5 °C	Values are calculated by the frequencies at +10, +25, +40°C with C-MOS circuit.
Temperature coefficient	a	-4.0 × 10 ⁻⁸ /°C ² Max.	
Isolation resistance	IR	500 MΩ Min.	DC 100V, 60 seconds Between terminal #1 and terminal #2
Aging	fa	± 3 × 10 ⁻⁶ /year	Ta = +25 °C ± 3 °C Drive level : 0.1 μW

[4] Environmental and Mechanical characteristics

No.	Items	Value	Conditions
1	Shock resistance	*3 Δ f/f : $\pm 8 \times 10^{-6}$	100g dummy(SEIKO EPSON Standard), Natural drop from 1500 mm height on to the concrete. 3 directions \times 10 times *2
2	Vibration resistance	*3 Δ f/f : $\pm 3 \times 10^{-6}$	10 Hz to 55 Hz amplitude 0.75 mm 55 Hz to 500 Hz acceleration 98 m/s ² 10 Hz \rightarrow 500 Hz \rightarrow 10 Hz 15 min./cycle 6 h (2 hours , 3 directions) *2
3	Soldering heat resistance	Δ f/f : $\pm 5 \times 10^{-6}$	For convention reflow soldering furnace (2 times)
4	High temperature storage	*3 Δ f/f : $\pm 10 \times 10^{-6}$	+125 °C \times 1000 h *1
		*3 Δ f/f : $\pm 7 \times 10^{-6}$	+85°C \times 1000 h *1
5	Low temperature storage	*3 Δ f/f : $\pm 10 \times 10^{-6}$	-55 °C \times 1000 h *1
6	High temperature and humidity	*3 Δ f/f : $\pm 10 \times 10^{-6}$	+85°C \times 85%RH \times 1000 h *1
7	Temperature cycle	*3 Δ f/f : $\pm 10 \times 10^{-6}$	-55 °C \leftrightarrow +125°C 30 minutes at each temperature \times 100 cycles *1
8	Sealing	*3 1×10^{-8} hPa \cdot l / s Max.	For He leak detector
9	Shear	No peeling-off at a soldered part	20 N press for 10 \pm 1 s. Ref. IEC 60068-2-21
10	Pull - off	No peeling-off at a soldered part	20 N press for 10 \pm 1 s. Ref. IEC 60068-2-21
11	Substrate bending	No peeling-off at a soldered part	Bend width reaches 3 mm and hold for 5 s \pm 1 s \times 1 time Ref. IEC 60068-2-21
12	Solvent resistance	The marking shall be legible	Ref. JIS C 0052 or IEC 60068-2-45

< Notes >

- *1 Each test done independently.
- *2 Measuring 2 h to 24 h later leaving in room temperature after each test. Drive level : 0.5 μ W
- *3 Pre conditionings(Treat the Reflow 2 times with the following profile) Initial value shall be after 24 h at room temperature.

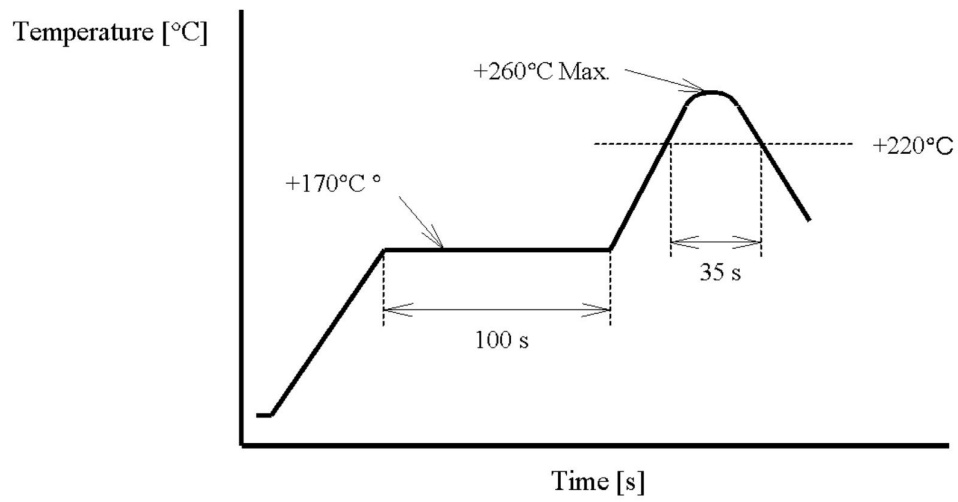
Shift of series resistance at before and after the test should be less than ± 20 % or less than ± 15 k Ω .

In case high temperature storage(+125°C \times 1 000 h), Soldering heat resistance, shift of series resistance at before and after the test should be less than ± 30 % or ± 20 k Ω .

◆ Air reflow

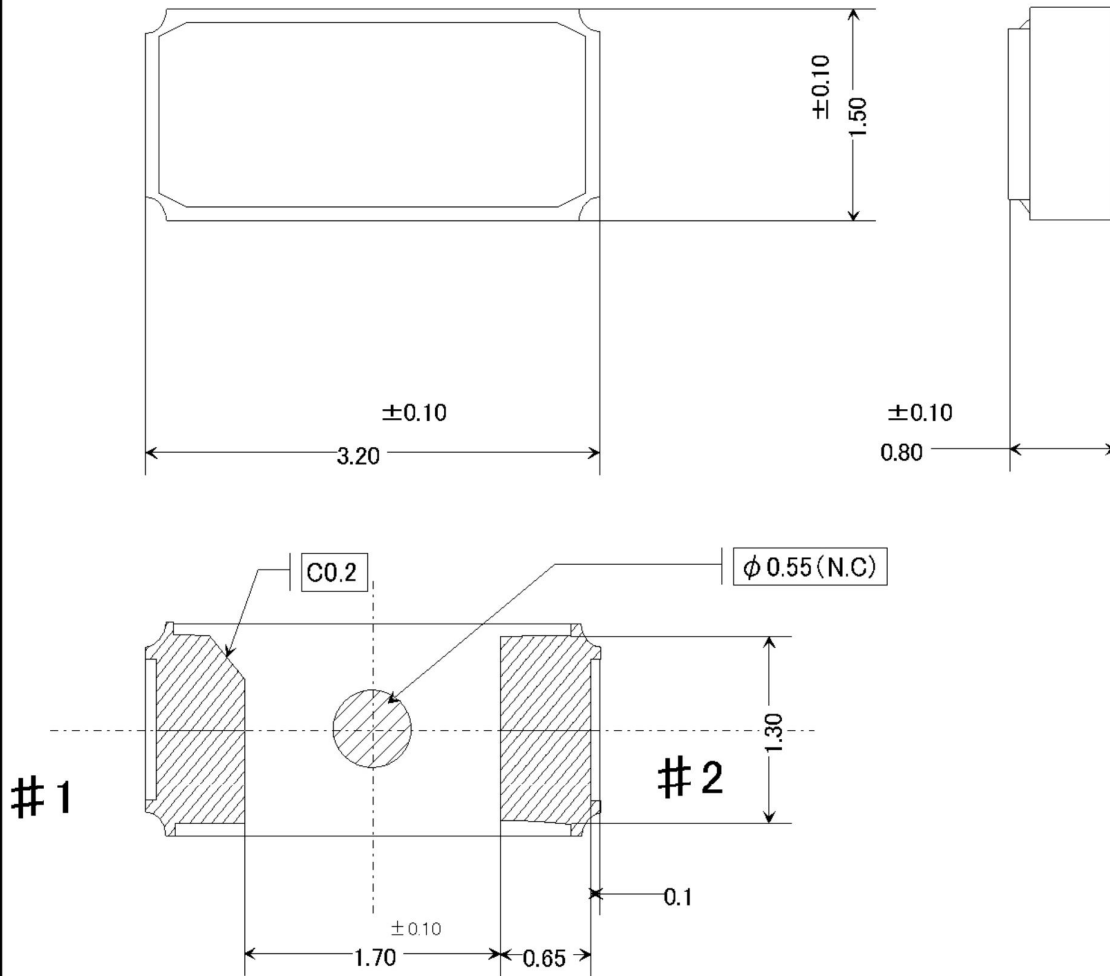
Pre heating temperature: +170 [°C]
Heating temperature : +220 [°C]

Pre heating time: 100 [s]
Heating time : 30 [s]

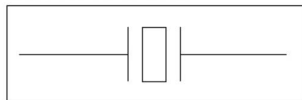


[5] Dimensions and Marking layout

1. Dimensions



2. Internal Connection



#1

#2

Package : Ceramic(Al_2O_3)

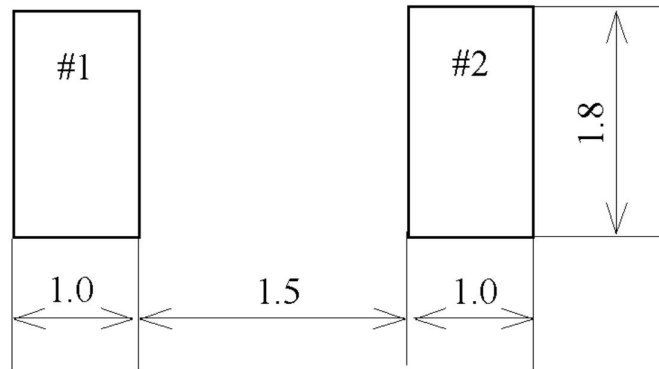
Terminal Au plating : 0.5 μm Min.

Lid : Glass

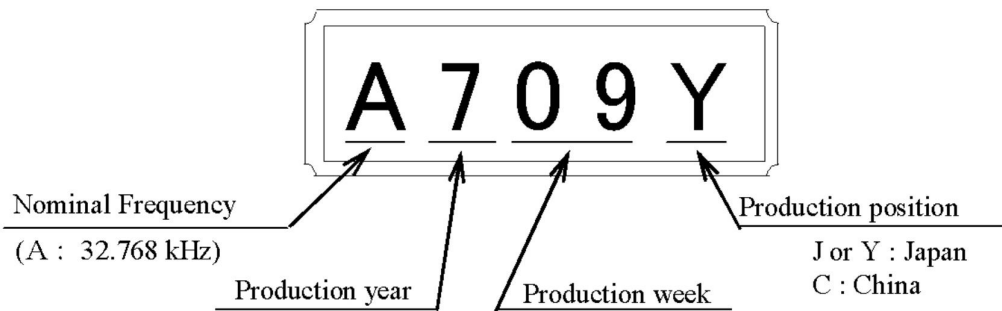
Type	FC-135	Terminal treatment	Au plating	Unit	1 = 1 mm
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3. Recommended soldering pattern

Unit : 1 = 1 mm



4. Marking layout



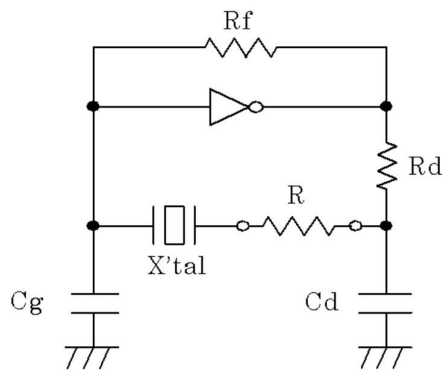
* The above marking layout shows only marking contents and their approximate position and it is not for font, size and exact position.

Type	FC-135	Unit	1=1 mm
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[6] Notes

1. Max two (2) times reflow is allowed. Once miss soldering is happened, hand work soldering by soldering iron is recommended. (+350°C × within 5 s)
2. Patterning should be followed by our recommended one.
3. Applying excessive excitation force to the crystal resonator may cause deterioration damage.
4. Unless adequate negative resistance is allocated in the oscillation circuit, start up time of oscillation may be increased, or no oscillation may occur.

How to check the negative resistance.



- (1) Connect the resistance (R) to the circuit in series with the crystal resonator.
- (2) Adjust R so that oscillation can start (or stop).
- (3) Measure R when oscillation just start (or stop) in above (2).
- (4) Get the negative resistance
 $-R = R + CI$ value.
- (5) Recommended -R
 $|-R| > CI \times (5 \sim 10)$

5. The shortest patterning line on board is recommendable.
Too long line on board may cause of abnormal oscillation.
6. To avoid mull function, no pattern under or near the crystal is allowed.
Solder paste should be more than 150 μm thickness.
7. This device must be stored at the normal temperature and humidity conditions before mounting on a board.
8. Too much exciting shock or vibration may cause deterioration on damage.
Depending on the condition such as a shock in assembly machinery, the products may be damaged.
Please check your condition in advance to maintain shock level to be smallest.
9. Depending on the conditions, ultrasonic cleaning may cause resonant damage of the internal crystal resonator. Since we are unable to determine the conditions (type of cleaning unit, power, time, conditions inside the bath, etc.) to be used in your company, we cannot guarantee the safety of this unit when it is cleaned in an ultrasonic cleaner.
10. Ink marking may be damaged by some kind of solvent, please take precautions when choosing solvent by your selves.
11. Please refer to packing specification regarding how to storage the products in the pack.